

PATENT APPLICATION
Docket No. 9903-070
Client No. S02US037

Applicant: Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn
Serial No. not yet assigned Examiner: not yet assigned
Filing Date: November 20, 2003 Art Unit: not yet assigned
Title: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

**INFORMATION DISCLOSURE CITATION
FORM PTO-1449 (Modified)**

U.S. PATENT DOCUMENTS

<u>Exam</u> <u>Init</u>	<u>Ref</u>	<u>Document</u> <u>Number</u>	<u>Issue</u> <u>Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub</u> <u>Class</u>
<u>TJ</u>	_____	US 6,294,838 B1	9/25/2001	Peng		

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<u>Exam</u> <u>Init</u>	<u>Ref</u>	<u>Document</u> <u>Number</u>	<u>Publication</u> <u>Date</u>	<u>Country</u>	<u>Name</u>
<u>TJ</u>	_____	2002-43395	6/10/2002	Korea	Eun-Yeong Jung
<u>TJ</u>	_____	2002-36191	5/16/2002	Korea	Beak, et al.

OTHER DOCUMENTS

<u>Exam</u> <u>Init</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
<u>TJ</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-43395 published 6/10/2002.
<u>TJ</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-36191, published 5/16/2002.

Examiner: Thompson
Date Considered: 10/27/04